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A wireless communication device comprising:

a housing including an upper surface, a lower surface, and at least one side intermediate the upper surface and the lower surface and having a dimension less than smallest dimensions of the upper surface and the lower surface, and the at least one side surface having visibly perceptible indicia thereon; and

communication circuitry within the housing and the communication circuitry being configured to communicate wireless signals.

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The device according to claim 53 wherein the housing comprises an encapsulant which contacts the communication circuitry.

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The device according to claim 53 wherein the at least one side surface has a dimension less than about 100 mils.

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The device according to claim 53 wherein the communication circuitry comprises radio frequency identification device circuitry.

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A wireless communication device comprising:

a substrate having a support surface defined by at least one
perimetral edge;

communication circuitry elevationally over the support surface of
the substrate and configured to communicate wireless signals; and

an encapsulant elevationally over the support surface and
configured to encapsulate at least portions of the support surface of the
substrate and the communication circuitry, and wherein the encapsulant
and the substrate respectively define an upper surface and a lower
surface and have a thickness less than a smallest dimension of the at
least one perimetral edge, and the encapsulant includes visibly
perceptible indicia intermediate the upper surface and the lower surface.

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The device according to claim 54 wherein the support
surface comprises a surface substantially in the shape of a rectangle.

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The device according to claim 55 wherein the encapsulant
contacts at least portions of the support surface and the communication
circuitry.

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The device according to claim 56 wherein the encapsulant
and the substrate have a thickness less than about 100 mils.

1. ~~58~~ ~~54~~ The device according to claim ~~57~~ wherein the communication
2. circuitry comprises radio frequency identification device circuitry.

3.
4. ~~59~~ ~~59~~ A wireless communication device comprising:
5. communication circuitry configured to communicate wireless signals;
6. and
7. an encapsulant configured to encapsulate and contact at least a
8. portion of the communication circuitry, wherein the encapsulant defines
9. at least one side surface and the at least one side surface has visibly
10. perceptible information thereon.

11. ~~60~~ ~~59~~
12. ~~60~~ ~~59~~ The device according to claim ~~62~~ wherein the encapsulant
13. has a thickness less than about 100 mils.

14.
15. ~~61~~ ~~59~~ The device according to claim ~~63~~ wherein the communication
16. circuitry comprises radio frequency identification device circuitry.

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~~61~~ ~~65~~ A radio frequency identification device comprising:

a housing including an upper surface and a lower surface which define a housing thickness of less than about 100 mils intermediate the lower surface and the upper surface, and the housing has visibly perceptible indicia thereon intermediate the upper surface and the lower surface; and

communication circuitry within the housing and configured to communicate wireless signals.

~~63~~ ~~66~~ The device according to claim ~~65~~ wherein the housing comprises an encapsulant which contacts at least portions of the support surface and the communication circuitry.

~~64~~ ~~67~~ The device according to claim ~~66~~ further comprising an antenna within the housing and coupled with the communication circuitry.

1 ~~66~~ 68 A method of forming a wireless communication device
2 comprising:

3 providing communication circuitry configured to communicate
4 wireless signals;

5 providing a housing including an upper surface, a lower surface
6 and at least one side surface about the communication circuitry, the at
7 least one side surface has a dimension less than smallest dimensions of
8 the upper surface and the lower surface; and

9 providing visibly perceptible indicia on the at least one side
10 surface.

11 ~~68~~ 70 The method according to claim ~~69~~ ⁶⁶ wherein the providing the
12 housing comprises encapsulating at least a portion of the communication
13 circuitry with an encapsulant.

14 ~~68~~ 71 The method according to claim ~~70~~ ⁶⁷ wherein the encapsulating
15 comprises contacting at least the encapsulated portion of the
16 communication circuitry with the encapsulant.

17 ~~69~~ 72 The method according to claim ~~69~~ ⁶⁶ wherein the at least one
18 side surface has a dimension less than about 100 mils.

71 74. A method of forming a wireless communication device comprising:

providing communication circuitry elevationally over the support surface of the substrate and configured to communicate wireless signals;

providing visibly perceptible indicia on the encapsulant intermediate the upper surface and the lower surface.

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1 ~~73~~ 76 The method according to claim ~~74~~ 71 wherein the encapsulating
2 comprises contacting at least the encapsulated portions of the support
3 surface of the substrate and, the communication circuitry with the
4 encapsulant.

5
6 ~~74~~ 71 The method according to claim ~~74~~ 71 wherein the encapsulant
7 and the substrate have a thickness less than about 100 mils.

8
9 ~~75~~ 78 The method according to claim ~~75~~ 74 wherein the providing
10 communication circuitry comprises providing radio frequency identification
11 device circuitry.

12
13 ~~76~~ 79 A method of forming a wireless communication device
14 comprising:

15 providing communication circuitry configured to communicate
16 wireless signals;

17 encapsulating at least a portion of the communication circuitry with
18 an encapsulant which contacts at least the encapsulated portion of the
19 communication circuitry, the encapsulant forming at least one side
20 surface; and

21 providing visibly perceptible indicia upon the at least one side
22 surface of the encapsulant.
23
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85. A method of forming a radio frequency identification device comprising:

coupling a power source with the radio frequency identification device circuitry;

providing a housing including an upper surface, a lower surface and at least one side surface about at least portions of the radio frequency identification device circuitry, the power source and the antenna, the at least one side surface having a dimension less than smallest dimensions of the upper surface and the lower surface; and

providing visibly perceptible indicia on the at least one side surface.